

**A vapour depositing method and an apparatus therefor.**

**A vapour depositing method and an apparatus therefor.**

Patent Number: ☐ EP0504886, B1

Publication date: 1992-09-23

Inventor(s): ONO SHOICHI (JP); IKEDA FUMIHIDE (JP); MIKOSHIBA NOBUO (JP); MUROTA JUNICHI (JP); SAKURABA MASAO (JP); KUROKAWA HARUSHIGE (JP)

Applicant(s): KOKUSAI ELECTRIC CO LTD (JP)

Requested Patent: ☐ JP4291916

Application Number: EP19920104795 19920319

Priority Number(s): JP19910056931 19910320

IPC Classification: C23C16/48; C30B25/10

EC Classification: C30B25/10B, C23C16/48D

EC Classification: C30B25/10B; C30B25/10B+29/08; C23C16/48D

Equivalents: DE69224541D, DE69224541T, JP2680202B2

**Abstract**

A vapor deposition apparatus and method in which pulse waveform light is applied to a sample sealed in a reaction chamber. The sample is exposed to gaseous material while the pulse waveform light is applied creating one or plural atomic layers. Alternate layers of plural substances or alternate multiple layers of plural substances can be formed by alternating the introduction of gaseous materials with the application of pulse waveform light.